

2SK2800

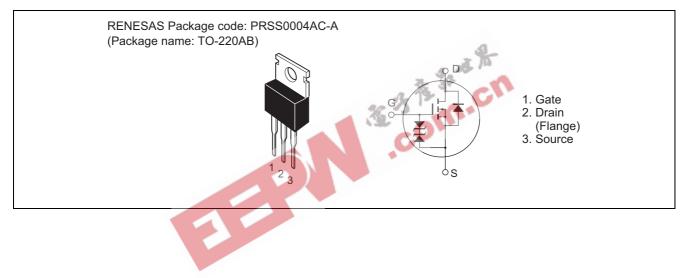
Silicon N Channel MOS FET High Speed Power Switching

> REJ03G1035-0900 (Previous: ADE-208-513G) Rev.9.00 Sep 07, 2005

Features

- Low on-resistance $R_{DS(on)} = 15 \text{ m}\Omega \text{ typ.}$
- High speed switching
- Low drive current
- 4 V gate drive device can be driven from 5 V source

Outline





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$	
Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	60	V	
Gate to source voltage	V _{GSS}	±20	V	
Drain current	ID	40	А	
Drain peak current	I _{D(pulse)} Note1	160	А	
Body-drain diode reverse drain current	I _{DR}	40	А	
Avalanche current	AP Note 3	40	А	
Avalanche energy	E _{AR} Note 3	137	mJ	
Channel dissipation	Pch Note 2	50	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. Value at Tc = 25°C

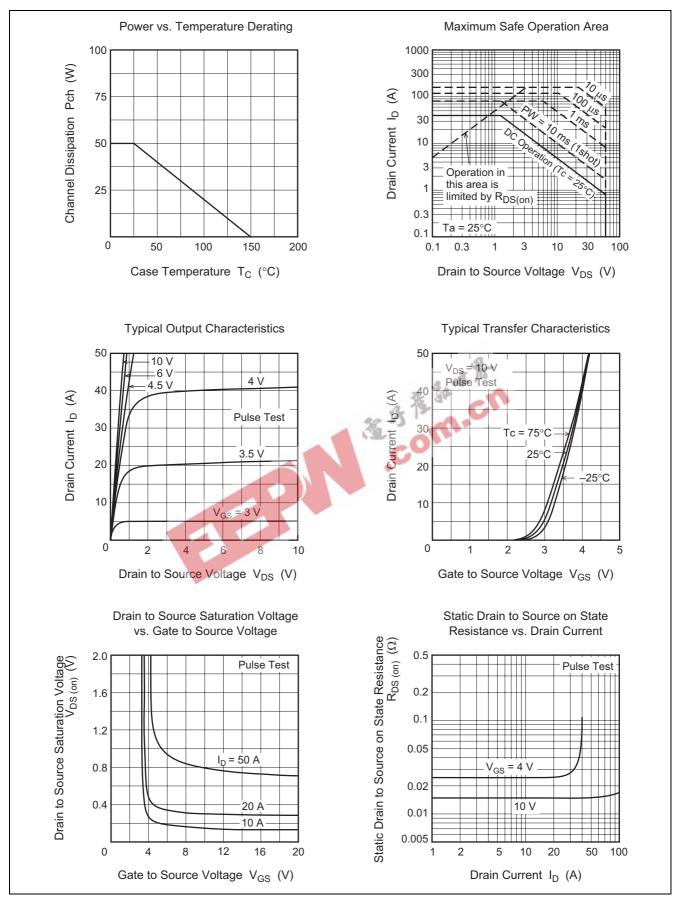
3. Value at Tch = 25° C, Rg $\geq 50\Omega$

Electrical Characteristics

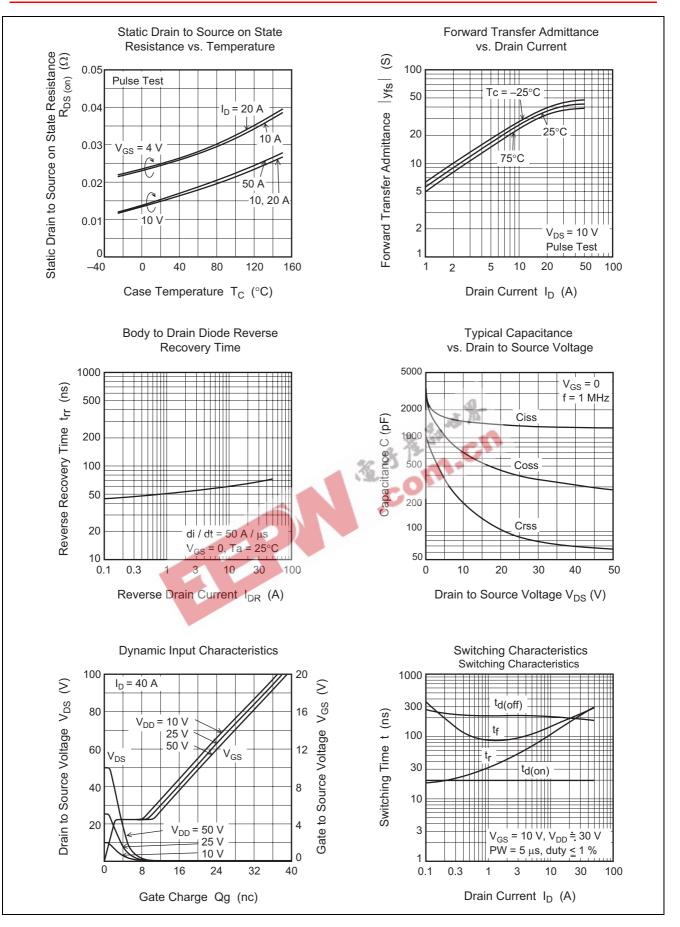
						$(Ta = 25^{\circ}C)$
ltem	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR)DSS}	60		_	V.	$I_{\rm D} = 10 \text{ mA}, V_{\rm GS} = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±20	_		V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	-	_	±10	μΑ 🦰	$V_{GS} = \pm 16 \text{ V}, \text{ V}_{DS} = 0$
Zero gate voltage drain current	I _{DSS}		-%	10	μΑ	$V_{DS} = 60 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	1.5	H , a	2.5	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{V}$
Static drain to source on state	R _{DS(on)}		15	20	mΩ	$I_D = 20 \text{ A}, V_{GS} = 10 \text{V}^{\text{Note4}}$
resistance	R _{DS(on)}	-+1	25	40	mΩ	$I_D = 20 \text{ A}, V_{GS} = 4 \text{ V}^{\text{Note4}}$
Forward transfer admittance	y _{fs}	20	35	—	S	$I_D = 20 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note4}}$
Input capacitance	Ciss		1500	_	pF	$V_{DS} = 10 V, V_{GS} = 0,$
Output capacitance	Coss	-	720	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	200	_	pF	
Turn-on delay time	t _{d(on)}	_	20	_	ns	I_D = 20 A, R _L = 1.5 Ω, V _{GS} = 10 V
Rise time	tr	_	180	_	ns	
Turn-off delay time	t _{d(off)}	_	200	_	ns	
Fall time	t _f	_	200		ns	
Body-drain diode forward voltage	V _{DF}	—	0.95	_	V	$I_F = 40 \text{ A}, V_{GS} = 0$
Body–drain diode reverse	t _{rr}	_	70		V	$I_F = 40 \text{ A}, V_{GS} = 0$
recovery time						di _F / dt =50 A/µs

Note: 4. Pulse test

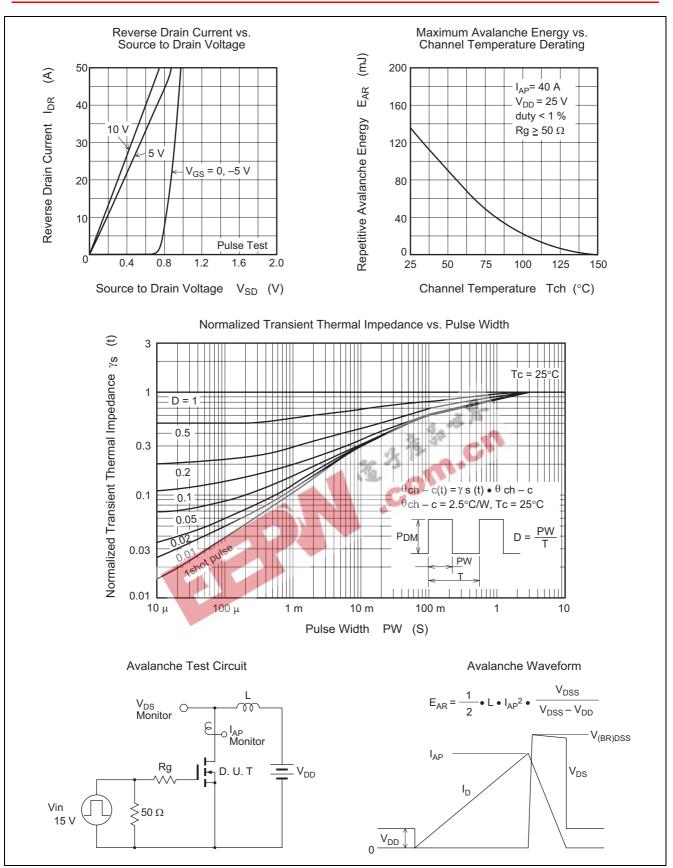
Main Characteristics



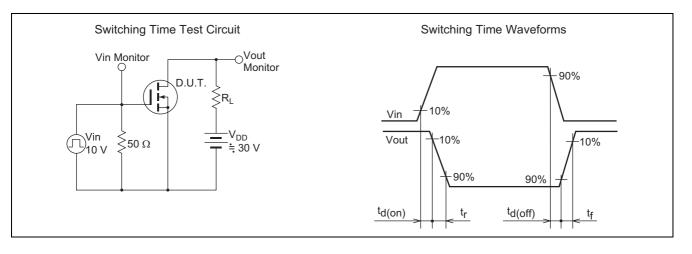








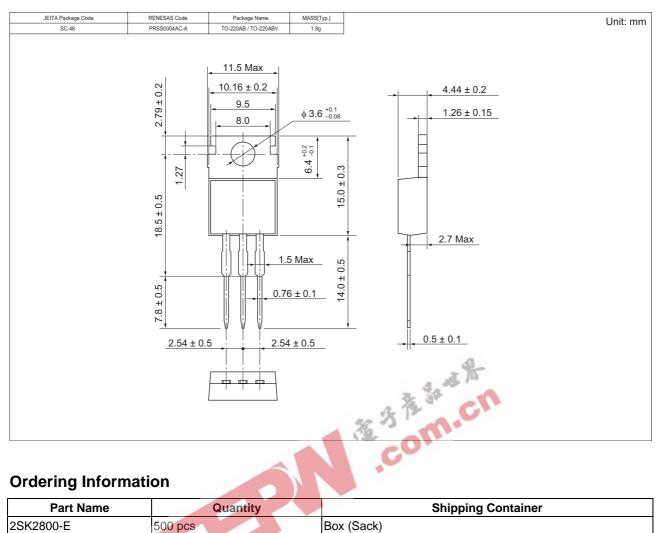








Package Dimensions



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